

LW A67C binning FK0PN0

SIDELED®



Applications

- Cluster, Button Backlighting
- Electronic Equipment
- Interior Illumination (e.g. Ambient Map)

Features:

- Package: white SMT package, colored diffused resin
- Chip technology: InGaN
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.33, Cy = 0.33 acc. to CIE 1931 (• white)
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Luminous Intensity ¹⁾ $I_F = 20 \text{ mA}$ I_v	Ordering Code
LW A67C-S2U2-FK0PN0-1	224 ... 710 mcd	Q65112A1368

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min.	-40 °C
		max.	100 °C
Storage Temperature	T_{stg}	min.	-40 °C
		max.	100 °C
Junction Temperature	T_j	max.	110 °C
Forward Current $T_s = 25\text{ °C}$	I_F	max.	20 mA
Surge Current $t \leq 10\text{ }\mu\text{s}$; $D = 0.005$; $T_s = 25\text{ °C}$	I_{FS}	max.	300 mA
Reverse voltage ²⁾ $T_s = 25\text{ °C}$	V_R	max.	5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV

Characteristics

$I_F = 20 \text{ mA}$; $T_S = 25 \text{ °C}$

Parameter	Symbol		Values
Chromaticity Coordinate ³⁾	C _x	typ.	0.33
	C _y	typ.	0.33
Viewing angle at 50 % I_v	2 ϕ	typ.	120 °
Forward Voltage ⁴⁾	V _F	min.	3.00 V
$I_F = 20 \text{ mA}$		typ.	3.20 V
		max.	3.90 V
Reverse current ²⁾	I _R	typ.	0.01 μA
V _R = 5 V		max.	10 μA
Real thermal resistance junction/ambient ^{5), 6)}	R _{thJA real}	max.	480 K / W
Real thermal resistance junction/solderpoint ⁵⁾	R _{thJS real}	max.	250 K / W

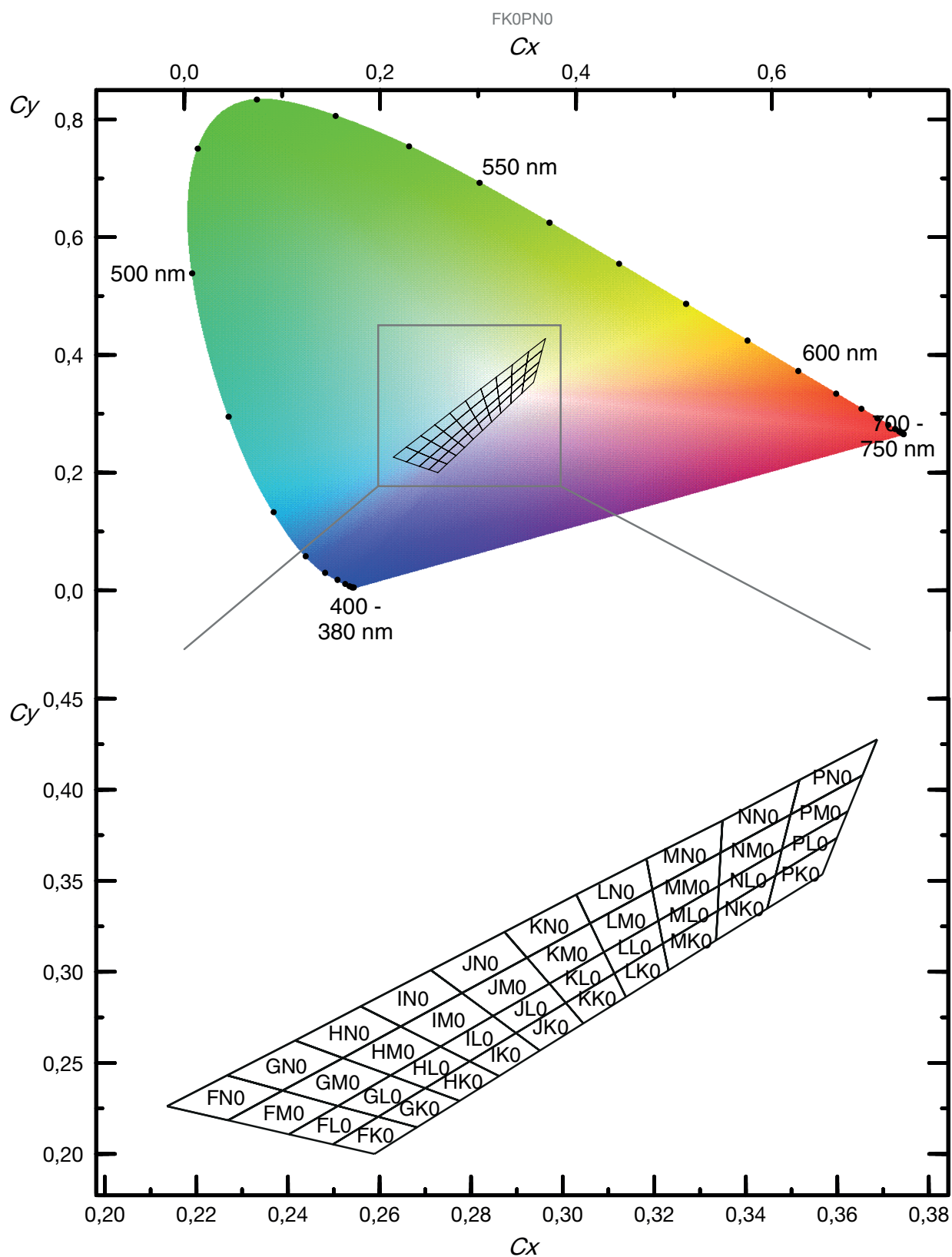
Brightness Groups

Group	Luminous Intensity ¹⁾ $I_F = 20 \text{ mA}$ min. I_v	Luminous Intensity ¹⁾ $I_F = 20 \text{ mA}$ max. I_v	Luminous Flux ⁷⁾ $I_F = 20 \text{ mA}$ typ. Φ_v
S2	224 mcd	280 mcd	760 mlm
T1	280 mcd	355 mcd	950 mlm
T2	355 mcd	450 mcd	1210 mlm
U1	450 mcd	560 mcd	1520 mlm
U2	560 mcd	710 mcd	1910 mlm

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ $I_F = 20 \text{ mA}$ min. V_F	Forward Voltage ⁴⁾ $I_F = 20 \text{ mA}$ max. V_F
66	3.00 V	3.30 V
C6	3.30 V	3.60 V
J6	3.60 V	3.90 V

Chromaticity Coordinate Groups



Color Chromaticity Groups ³⁾

Group	Cx	Cy	Group	Cx	Cy	Group	Cx	Cy
FK0	0.2498	0.2053	HK0	0.2700	0.2361	JK0	0.2898	0.2664
	0.2597	0.2204		0.2797	0.2509		0.3007	0.2830
	0.2682	0.2146		0.2861	0.2427		0.3045	0.2717
	0.2589	0.2000		0.2775	0.2292		0.2950	0.2568
FL0	0.2402	0.2108	HL0	0.2624	0.2431	JL0	0.2848	0.2757
	0.2509	0.2264		0.2733	0.2590		0.2971	0.2935
	0.2597	0.2204		0.2797	0.2509		0.3007	0.2830
	0.2498	0.2053		0.2700	0.2361		0.2898	0.2664
FM0	0.2269	0.2185	HM0	0.2520	0.2527	JM0	0.2780	0.2883
	0.2388	0.2348		0.2646	0.2700		0.2922	0.3077
	0.2509	0.2264		0.2733	0.2590		0.2971	0.2935
	0.2402	0.2108		0.2624	0.2431		0.2848	0.2757
FN0	0.2136	0.2262	HN0	0.2416	0.2623	JN0	0.2712	0.3009
	0.2267	0.2432		0.2559	0.2810		0.2873	0.3219
	0.2388	0.2348		0.2646	0.2700		0.2922	0.3077
	0.2269	0.2185		0.2520	0.2527		0.2780	0.2883
GK0	0.2597	0.2204	IK0	0.2797	0.2509	KK0	0.3007	0.2830
	0.2700	0.2361		0.2898	0.2664		0.3113	0.2992
	0.2775	0.2292		0.2950	0.2568		0.3138	0.2862
	0.2682	0.2146		0.2861	0.2427		0.3045	0.2717
GL0	0.2509	0.2264	IL0	0.2733	0.2590	KL0	0.2971	0.2935
	0.2624	0.2431		0.2848	0.2757		0.3090	0.3108
	0.2700	0.2361		0.2898	0.2664		0.3113	0.2992
	0.2597	0.2204		0.2797	0.2509		0.3007	0.2830
GM0	0.2388	0.2348	IM0	0.2646	0.2700	KM0	0.2922	0.3077
	0.2520	0.2527		0.2780	0.2883		0.3060	0.3266
	0.2624	0.2431		0.2848	0.2757		0.3090	0.3108
	0.2509	0.2264		0.2733	0.2590		0.2971	0.2935
GN0	0.2267	0.2432	IN0	0.2559	0.2810	KN0	0.2873	0.3219
	0.2416	0.2623		0.2712	0.3009		0.3030	0.3424
	0.2520	0.2527		0.2780	0.2883		0.3060	0.3266
	0.2388	0.2348		0.2646	0.2700		0.2922	0.3077

Group	Cx	Cy	Group	Cx	Cy	Group	Cx	Cy
LK0	0.3113	0.2992	MM0	0.3196	0.3451	PK0	0.3465	0.3530
	0.3219	0.3154		0.3345	0.3654		0.3599	0.3735
	0.3231	0.3008		0.3341	0.3472		0.3567	0.3535
	0.3138	0.2862		0.3209	0.3281		0.3447	0.3347
LL0	0.3090	0.3108	MN0	0.3183	0.3621	PL0	0.3479	0.3673
	0.3209	0.3281		0.3349	0.3830		0.3623	0.3882
	0.3219	0.3154		0.3345	0.3654		0.3599	0.3735
	0.3113	0.2992		0.3196	0.3451		0.3465	0.3530
LM0	0.3060	0.3266	NK0	0.3339	0.3336	PM0	0.3498	0.3863
	0.3196	0.3451		0.3465	0.3530		0.3655	0.4079
	0.3209	0.3281		0.3447	0.3347		0.3623	0.3882
	0.3090	0.3108		0.3335	0.3172		0.3479	0.3673
LN0	0.3030	0.3424	NLO	0.3341	0.3472	PN0	0.3517	0.4053
	0.3183	0.3621		0.3479	0.3673		0.3687	0.4276
	0.3196	0.3451		0.3465	0.3530		0.3655	0.4079
	0.3060	0.3266		0.3339	0.3336		0.3498	0.3863
MK0	0.3219	0.3154	NMO	0.3345	0.3654			
	0.3339	0.3336		0.3498	0.3863			
	0.3335	0.3172		0.3479	0.3673			
	0.3231	0.3008		0.3341	0.3472			
ML0	0.3209	0.3281	NNO	0.3349	0.3830			
	0.3341	0.3472		0.3517	0.4053			
	0.3339	0.3336		0.3498	0.3863			
	0.3219	0.3154		0.3345	0.3654			

Group Name on Label

Example: S2-FK0-66

Brightness

Color Chromaticity

Forward Voltage

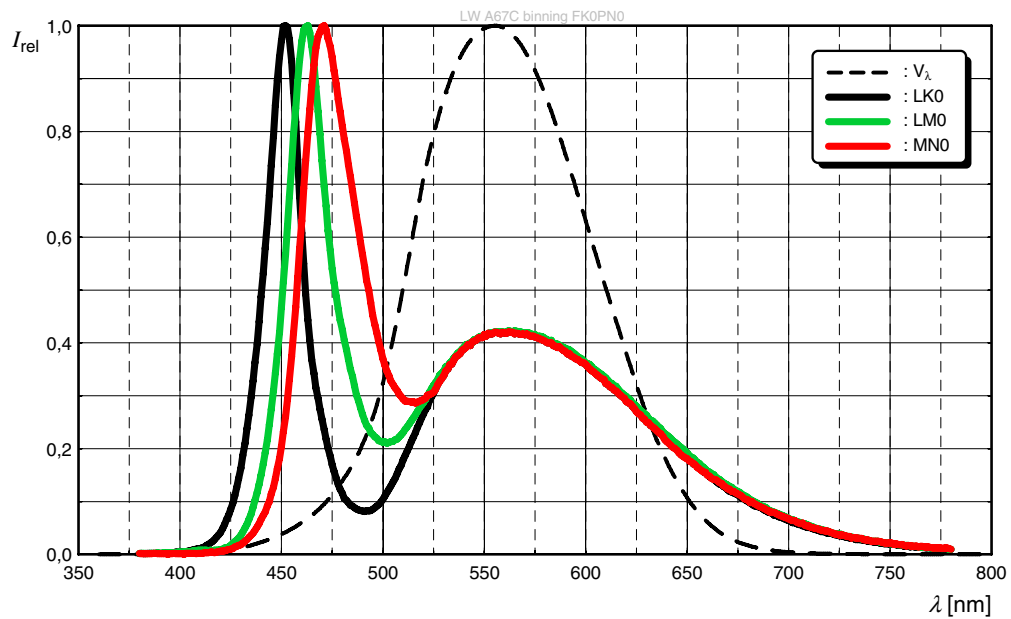
S2

FK0

66

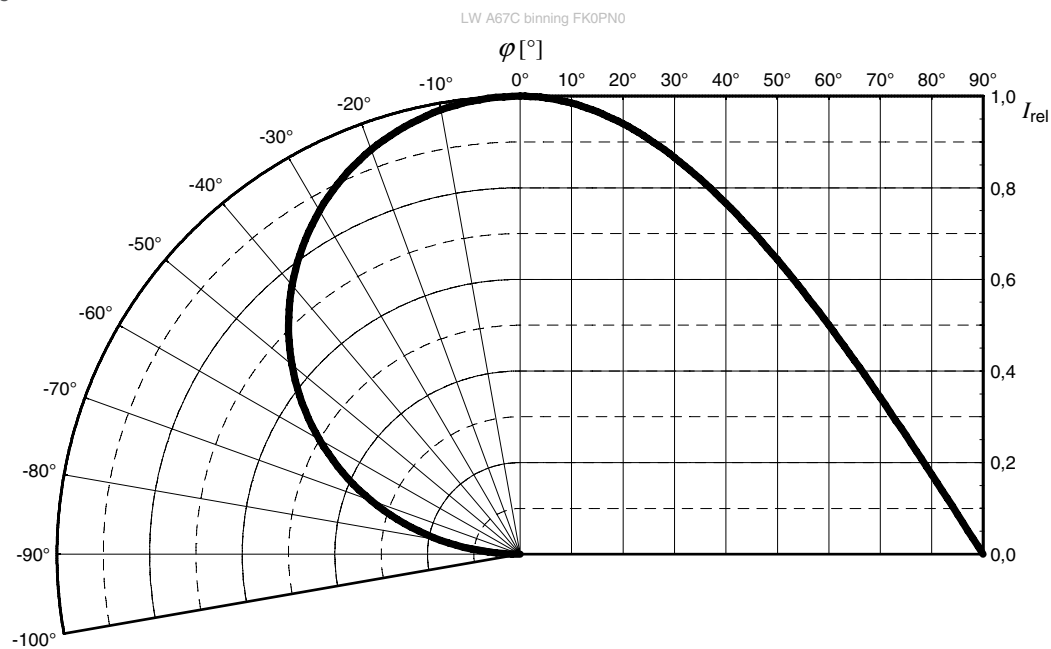
Relative Spectral Emission ⁷⁾

$$I_{\text{rel}} = f(\lambda); I_F = 20 \text{ mA}; T_S = 25 \text{ °C}$$



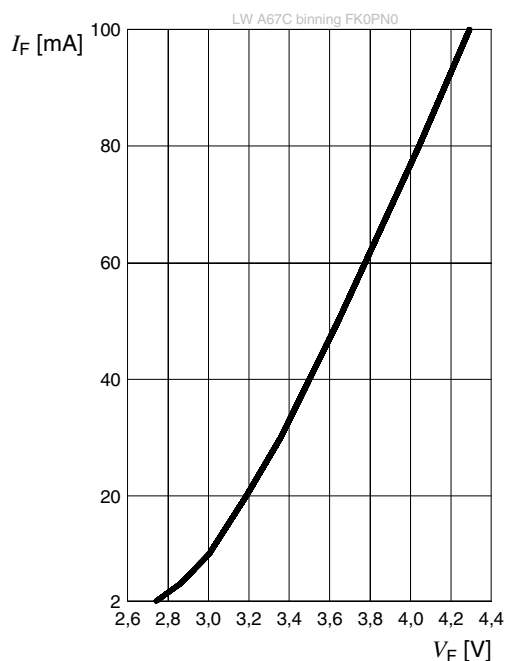
Radiation Characteristics ⁷⁾

$$I_{\text{rel}} = f(\phi); T_S = 25 \text{ °C}$$

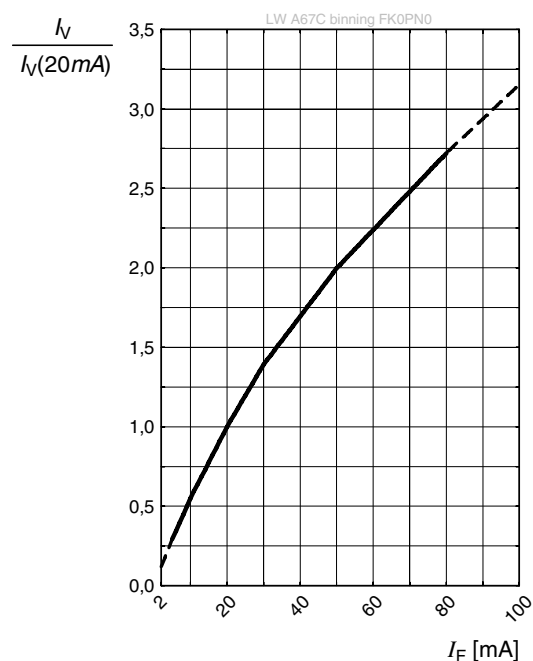


Forward current ⁷⁾

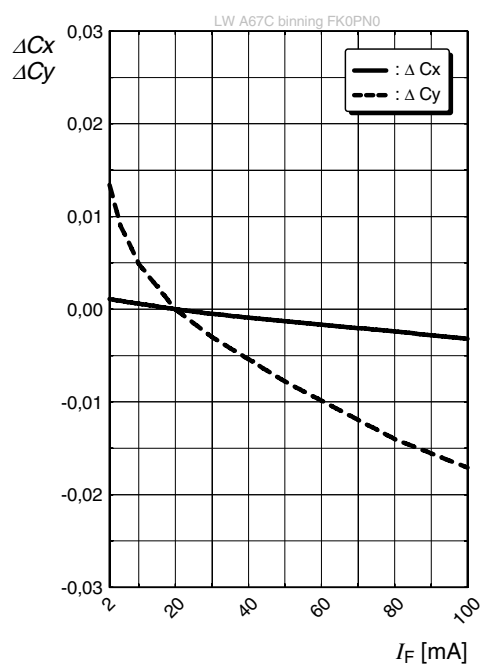
$$I_F = f(V_F); T_S = 25\text{ °C}$$

**Relative Luminous Intensity** ^{7), 8)}

$$I_V/I_V(20\text{ mA}) = f(I_F); T_S = 25\text{ °C}$$

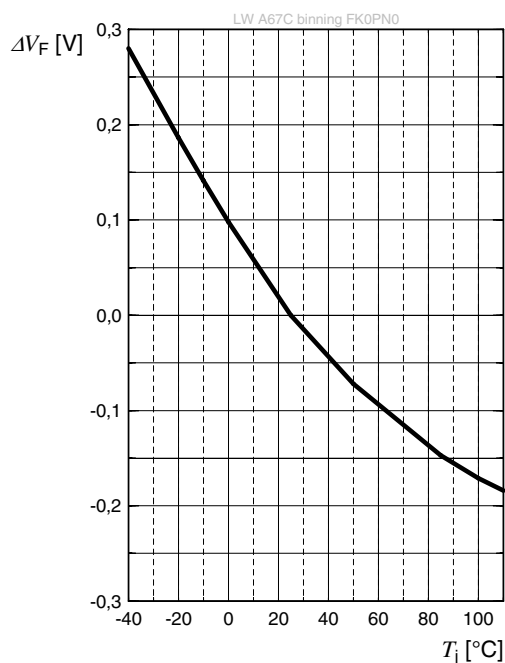
**Chromaticity Coordinate Shift** ⁷⁾

$$\Delta C_x, \Delta C_y = f(I_F); T_S = 25\text{ °C}$$



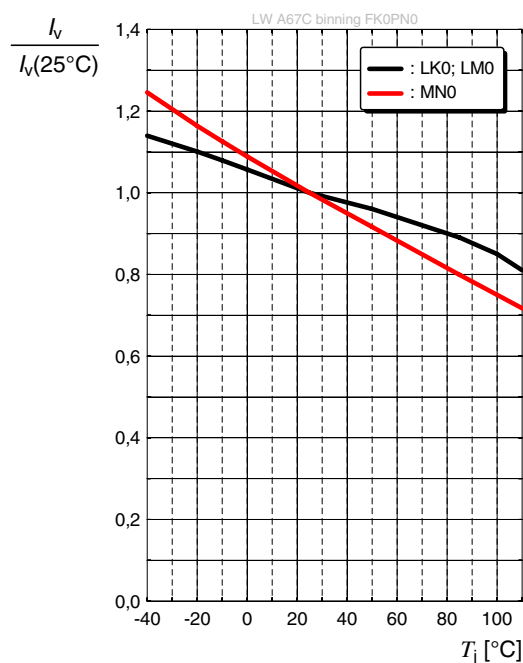
Forward Voltage ⁷⁾

$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 20\text{ mA}$$



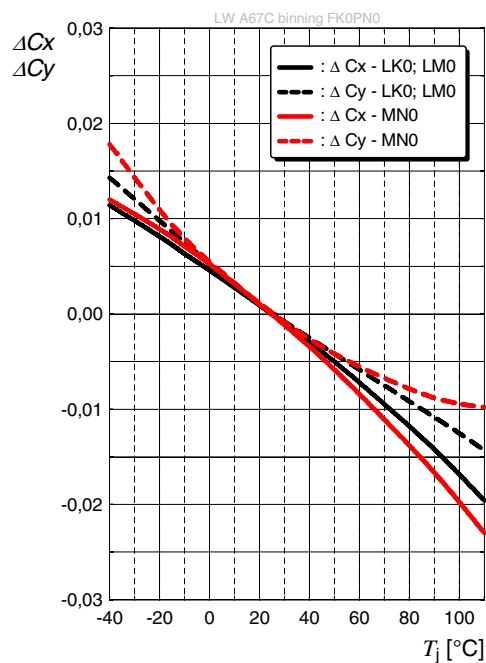
Relative Luminous Intensity ⁷⁾

$$I_V/I_V(25^\circ\text{C}) = f(T_j); I_F = 20\text{ mA}$$



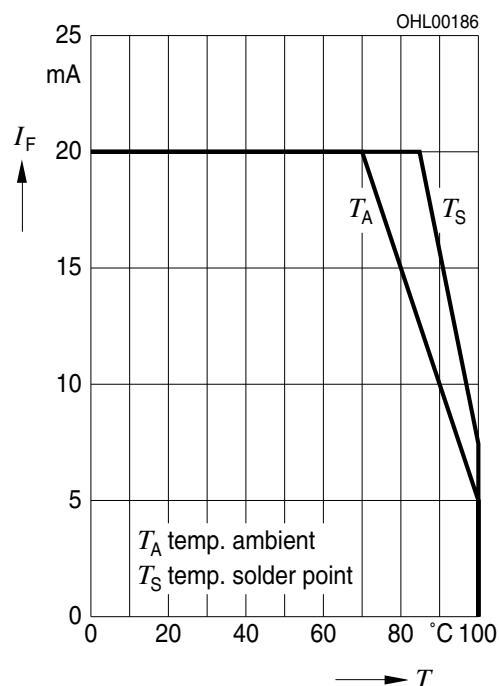
Chromaticity Coordinate Shift ⁷⁾

$$\Delta C_x, \Delta C_y = f(T_j); I_F = 20\text{ mA}$$



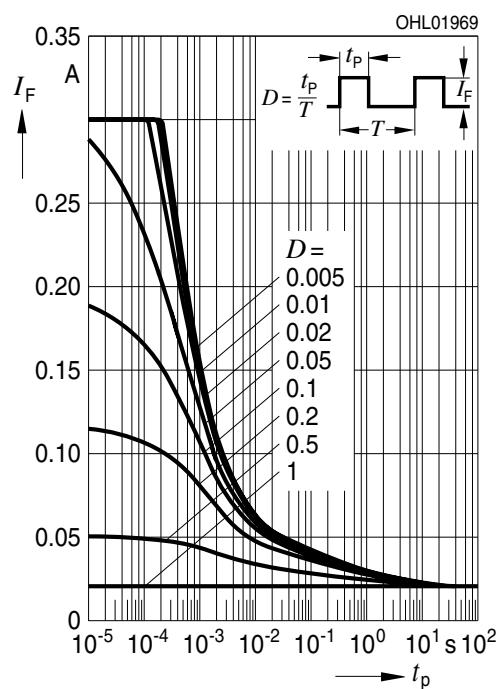
Max. Permissible Forward Current

$$I_F = f(T)$$



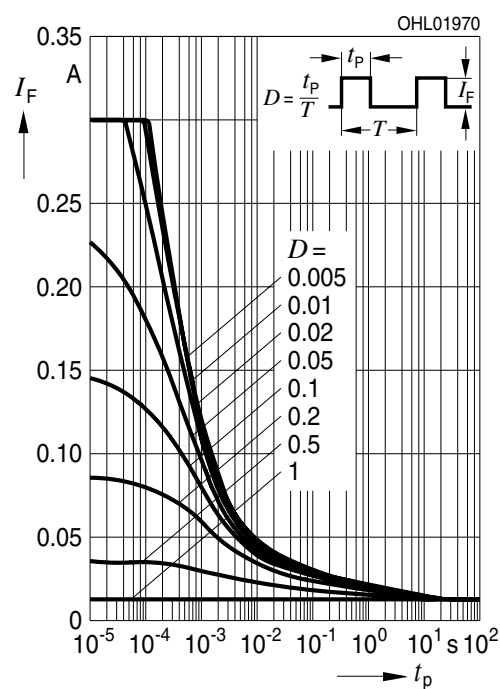
Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}; T_S = 25^\circ\text{C}$$

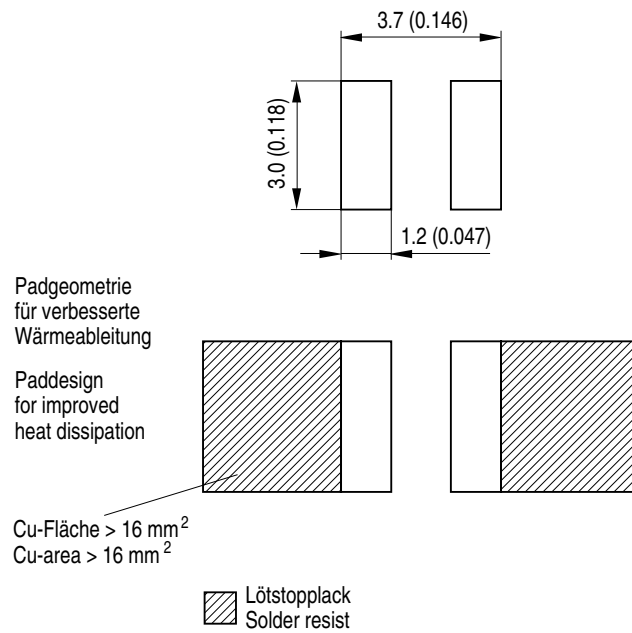


Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}; T_S = 85^\circ\text{C}$$



Recommended Solder Pad ⁹⁾

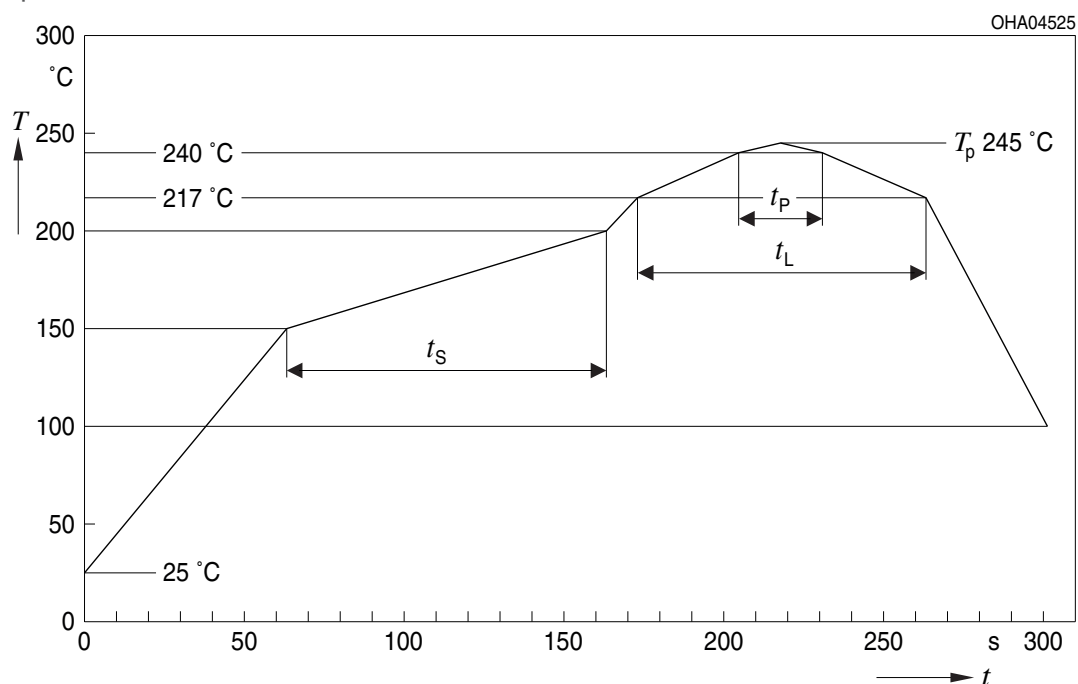


OHLPY965

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

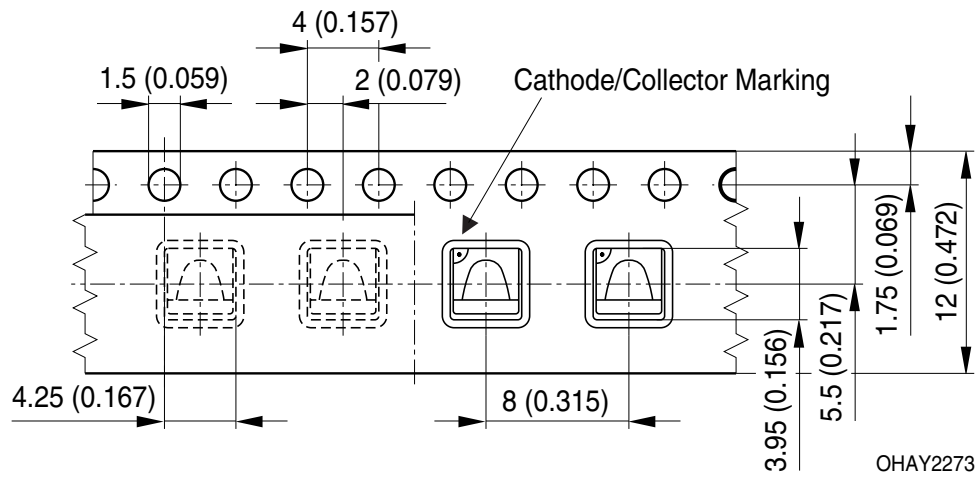


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		$^{\circ}\text{C}$
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	250	$^{\circ}\text{C}$
Time within 5 °C of the specified peak temperature $T_p - 5\text{ K}$	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	4	K/s
Time 25 °C to T_p				480	s

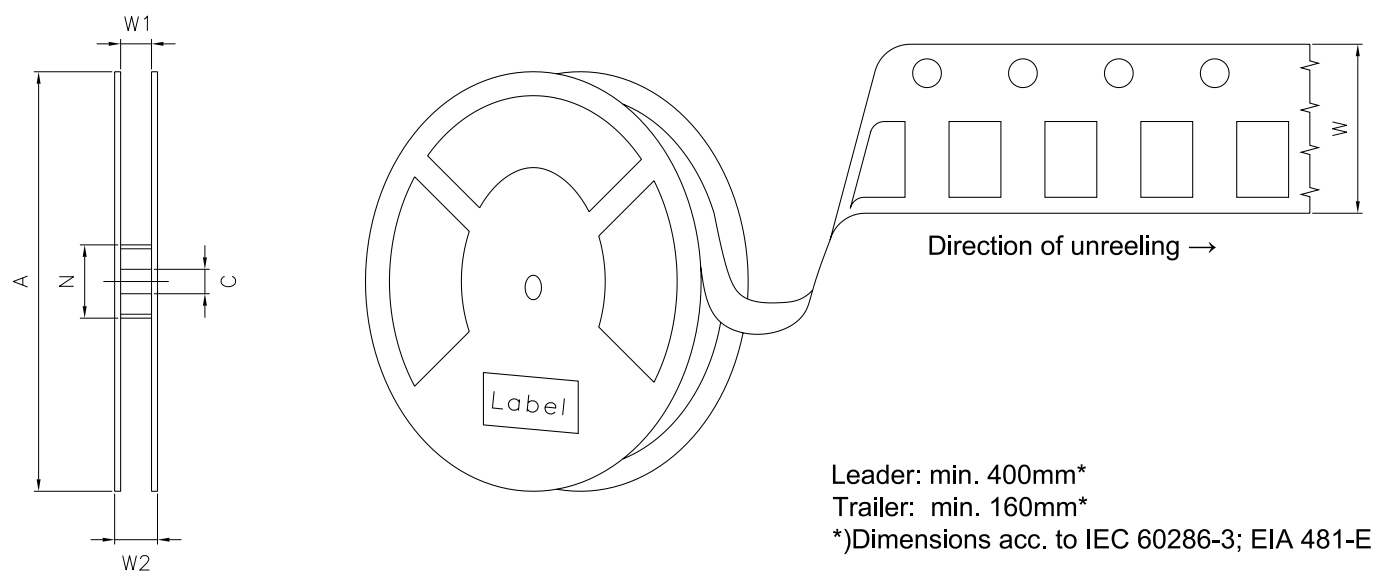
All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T -range

Taping ⁹⁾



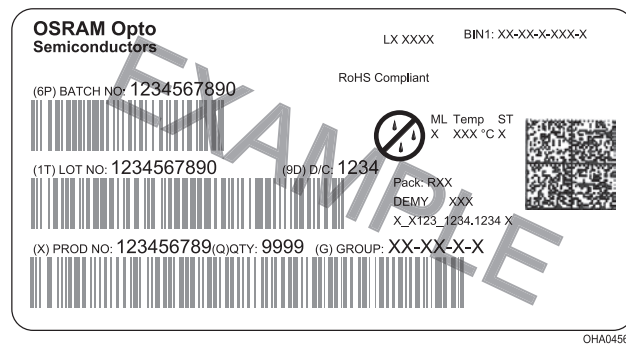
Tape and Reel ¹⁰⁾



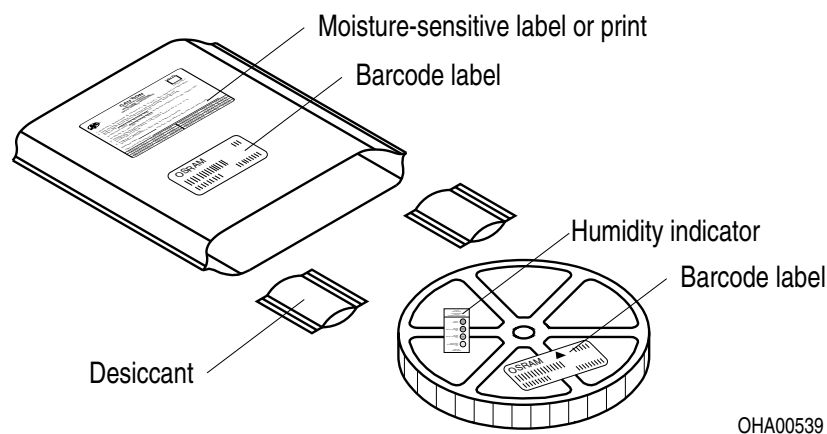
Reel dimensions [mm]

A	W	N _{min}	W ₁	W _{2 max}	Pieces per PU
330 mm	12 + 0.3 / - 0.1	60	12.4 + 2	18.4	2000

Barcode-Product-Label (BPL)

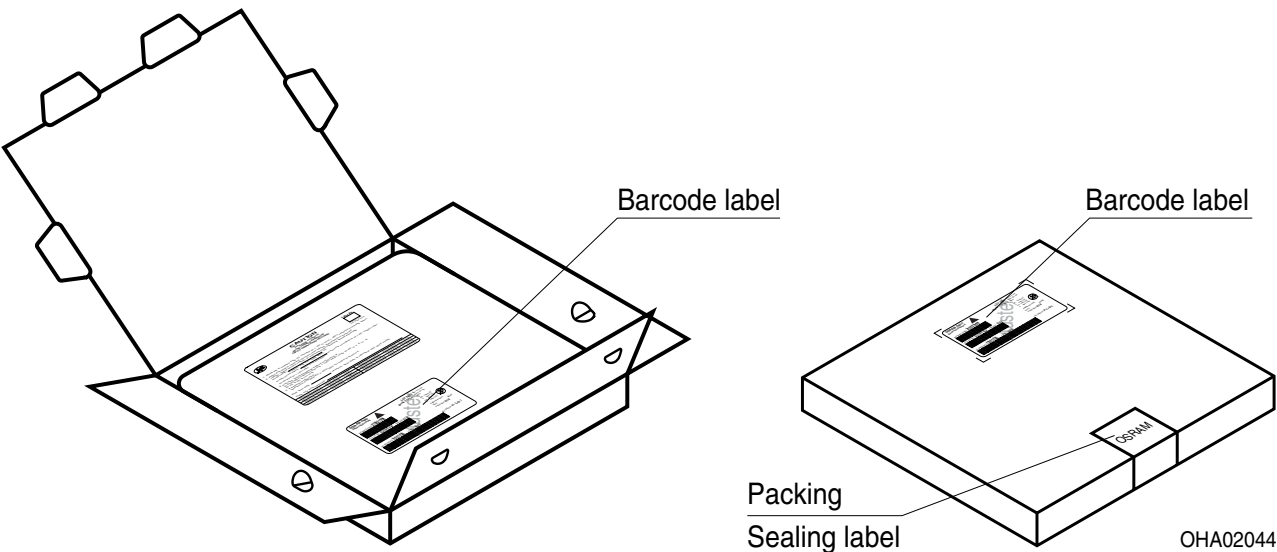


Dry Packing Process and Materials ⁹⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Transportation Packing and Materials ⁹⁾



Dimensions of transportation box in mm

Width	Length	Height
349 ± 5 mm	349 ± 5 mm	33 ± 5 mm

Type Designation System

Wavelength ($\lambda_{\text{dom typ.}}$)		Emission Color	Color coordinates according CIE 1931/Emission color:			
A:	617 nm	amber	W:	white		
S:	633 nm	super red	UW:	ultra white		
T:	528 nm	true green	CB:	color on demand blue		
Y:	587 nm	yellow	CG:	color on demand green		
O:	606 nm	orange	CL:	color on demand lagune		
G:	570 nm	green	Package Type A: SIDELED			
P:	560 nm	pure green				
R:	625 nm	red				
B:	470 nm	blue				
H:	645 nm	hyper-red				
V:	505 nm	verde green				
L: Light emitting diode						
L	A		A	6	7	6
Lead / Package Properties 6: folded leads						
Encapsulant Type / Lens Properties 7: Colorless clear or white volume conversion (resin encapsulation) S: Silicone (with or without diffuser)						
Chip Technology: 3: standard InGaN 6: Standard InGaIP B: HOP 2000 C: ATON F: Thinfilm InGaAIP G: ThinGaN(Thinfilm InGaN) (Subcon:Sapphire) K: InGaAIP low current						

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes

Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of $\pm 8\%$ and an expanded uncertainty of $\pm 11\%$ (acc. to GUM with a coverage factor of $k = 3$).
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 0.005 and an expanded uncertainty of ± 0.01 (acc. to GUM with a coverage factor of $k = 3$).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of $\pm 0.05\text{ V}$ and an expanded uncertainty of $\pm 0.1\text{ V}$ (acc. to GUM with a coverage factor of $k = 3$).
- 5) **Thermal Resistance:** $R_{th\text{ max}}$ is based on statistic values (6σ).
- 6) **Thermal Resistance:** R_{thJA} results from mounting on PC board FR 4 (pad size 16 mm^2 per pad)
- 7) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 8) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

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EU RoHS and China RoHS compliant product



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按照中国的相关法规和标准，不含有毒有害物质或元素。

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Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели,
кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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